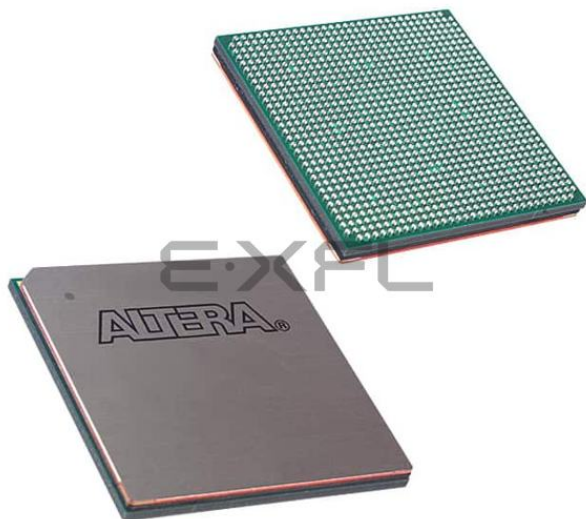




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	7904
Number of Logic Elements/Cells	79040
Total RAM Bits	7427520
Number of I/O	773
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA
Supplier Device Package	1020-FBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s80f1020c5n

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Introduction

The Stratix® family of FPGAs is based on a 1.5-V, 0.13-µm, all-layer copper SRAM process, with densities of up to 79,040 logic elements (LEs) and up to 7.5 Mbits of RAM. Stratix devices offer up to 22 digital signal processing (DSP) blocks with up to 176 (9-bit × 9-bit) embedded multipliers, optimized for DSP applications that enable efficient implementation of high-performance filters and multipliers. Stratix devices support various I/O standards and also offer a complete clock management solution with its hierarchical clock structure with up to 420-MHz performance and up to 12 phase-locked loops (PLLs).

The following shows the main sections in the Stratix Device Family Data Sheet:

Section	Page
Features	1-2
Functional Description	2-1
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Stratix devices are available in space-saving FineLine BGA® and ball-grid array (BGA) packages (see [Tables 1–3](#) through [1–5](#)). All Stratix devices support vertical migration within the same package (for example, you can migrate between the EP1S10, EP1S20, and EP1S25 devices in the 672-pin BGA package). Vertical migration means that you can migrate to devices whose dedicated pins, configuration pins, and power pins are the same for a given package across device densities. For I/O pin migration across densities, you must cross-reference the available I/O pins using the device pin-outs for all planned densities of a given package type to identify which I/O pins are migrational. The Quartus® II software can automatically cross reference and place all pins except differential pins for migration when given a device migration list. You must use the pin-outs for each device to verify the differential placement migration. A future version of the Quartus II software will support differential pin migration.

Table 1–3. Stratix Package Options & I/O Pin Counts

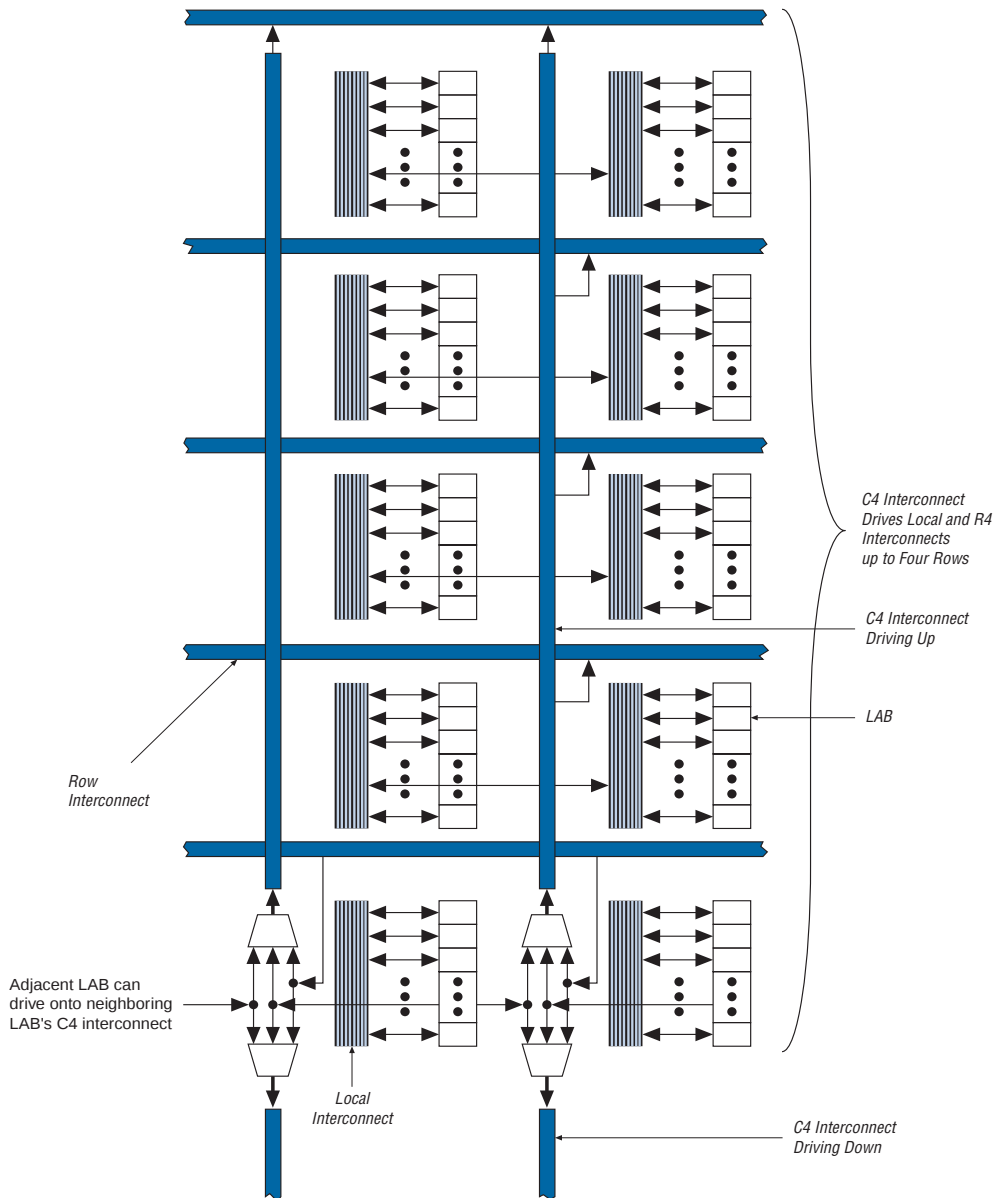
Device	672-Pin BGA	956-Pin BGA	484-Pin FineLine BGA	672-Pin FineLine BGA	780-Pin FineLine BGA	1,020-Pin FineLine BGA	1,508-Pin FineLine BGA
EP1S10	345		335	345	426		
EP1S20	426		361	426	586		
EP1S25	473			473	597	706	
EP1S30		683			597	726	
EP1S40		683			615	773	822
EP1S60		683				773	1,022
EP1S80		683				773	1,203

Note to [Table 1–3](#):

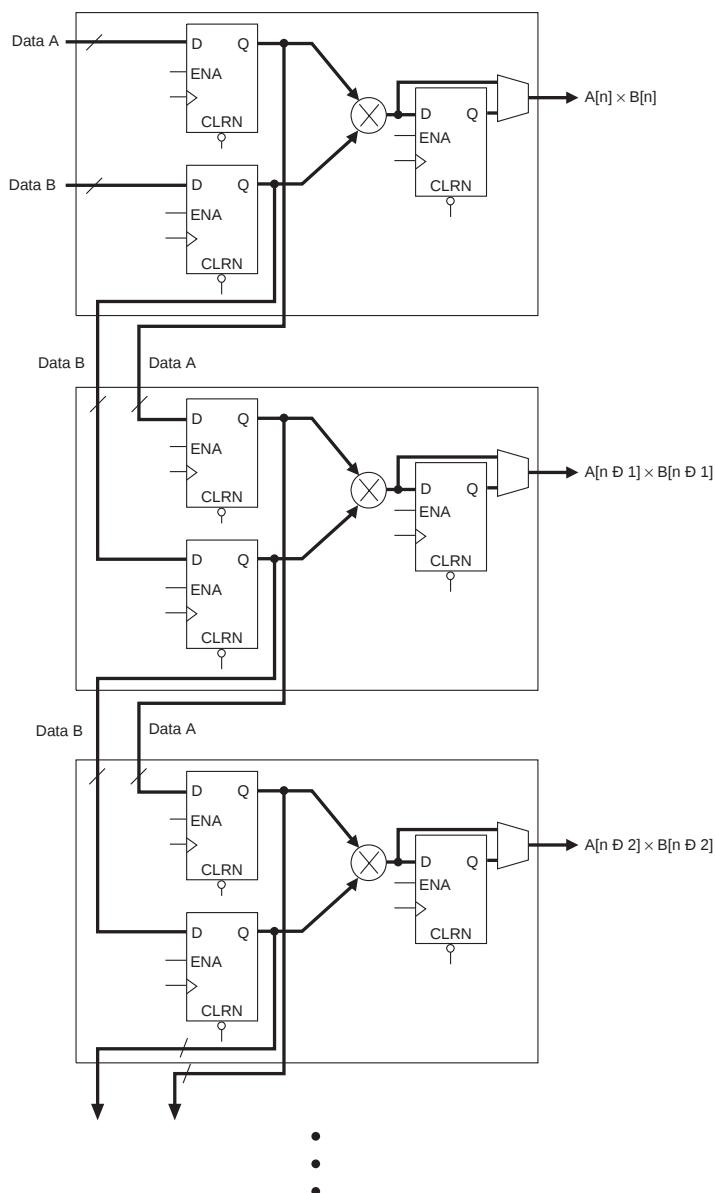
- (1) All I/O pin counts include 20 dedicated clock input pins (clk[15..0]p, clk0n, clk2n, clk9n, and clk11n) that can be used for data inputs.

Table 1–4. Stratix BGA Package Sizes

Dimension	672 Pin	956 Pin
Pitch (mm)	1.27	1.27
Area (mm ²)	1,225	1,600
Length × width (mm × mm)	35 × 35	40 × 40

Figure 2–11. C4 Interconnect Connections *Note (1)***Note to Figure 2–11:**

(1) Each C4 interconnect can drive either up or down four rows.

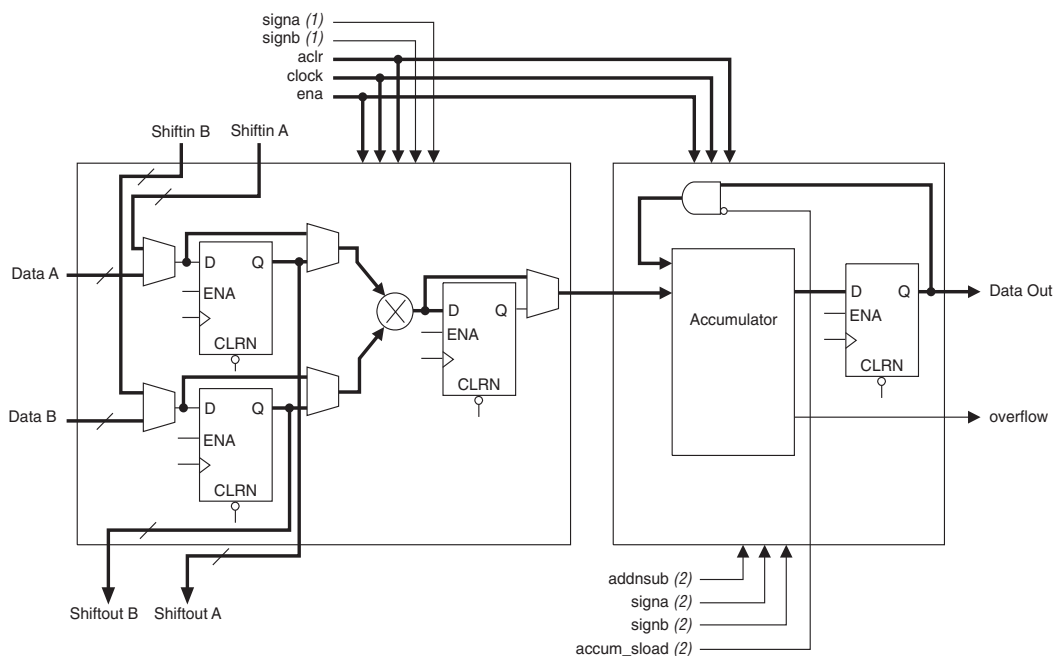
Figure 2–33. Multiplier Sub-Blocks Using Input Shift Register Connections*Note (1)***Note to Figure 2–33:**

- (1) Either Data A or Data B input can be set to a parallel input for constant coefficient multiplication.

Multiply-Accumulator Mode

In multiply-accumulator mode (see Figure 2–37), the DSP block drives multiplied results to the adder/subtractor/accumulator block configured as an accumulator. You can implement one or two multiply-accumulators up to 18×18 bits in one DSP block. The first and third multiplier sub-blocks are unused in this mode, because only one multiplier can feed one of two accumulators. The multiply-accumulator output can be up to 52 bits—a maximum of a 36-bit result with 16 bits of accumulation. The `accum_load` and `overflow` signals are only available in this mode. The `addnsub` signal can set the accumulator for decimation and the `overflow` signal indicates underflow condition.

Figure 2–37. Multiply-Accumulate Mode



Notes to Figure 2–37:

- (1) These signals are not registered or registered once to match the data path pipeline.
- (2) These signals are not registered, registered once, or registered twice for latency to match the data path pipeline.

Two-Multipliers Adder Mode

The two-multipliers adder mode uses the adder/subtractor/accumulator block to add or subtract the outputs of the multiplier block, which is useful for applications such as FFT functions and complex FIR filters. A

provide general purpose clocking with multiplication and phase shifting as well as high-speed outputs for high-speed differential I/O support. Enhanced and fast PLLs work together with the Stratix high-speed I/O and advanced clock architecture to provide significant improvements in system performance and bandwidth.

The Quartus II software enables the PLLs and their features without requiring any external devices. Table 2–18 shows the PLLs available for each Stratix device.

Table 2–18. Stratix Device PLL Availability

Device	Fast PLLs								Enhanced PLLs			
	1	2	3	4	7	8	9	10	5(1)	6(1)	11(2)	12(2)
EP1S10	✓	✓	✓	✓					✓	✓		
EP1S20	✓	✓	✓	✓					✓	✓		
EP1S25	✓	✓	✓	✓					✓	✓		
EP1S30	✓	✓	✓	✓	✓ (3)	✓ (3)	✓ (3)	✓ (3)	✓	✓		
EP1S40	✓	✓	✓	✓	✓ (3)	✓ (3)	✓ (3)	✓ (3)	✓	✓	✓ (3)	✓ (3)
EP1S60	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
EP1S80	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Notes to Table 2–18:

- (1) PLLs 5 and 6 each have eight single-ended outputs or four differential outputs.
- (2) PLLs 11 and 12 each have one single-ended output.
- (3) EP1S30 and EP1S40 devices do not support these PLLs in the 780-pin FineLine BGA® package.

VCO period from up to eight taps for individual fine step selection. Also, each clock output counter can use a unique initial count setting to achieve individual coarse shift selection in steps of one VCO period. The combination of coarse and fine shifts allows phase shifting for the entire input clock period.

The equation to determine the precision of the phase shifting in degrees is: $45^\circ \div \text{post-scale counter value}$. Therefore, the maximum step size is 45° , and smaller steps are possible depending on the multiplication and division ratio necessary on the output counter port.

This type of phase shift provides the highest precision since it is the least sensitive to process, supply, and temperature variation.

Clock Delay

In addition to the phase shift feature, the ability to fine tune the Δt clock delay provides advanced time delay shift control on each of the four PLL outputs. There are time delays for each post-scale counter (e , g , or l) from the PLL, the n counter, and m counter. Each of these can shift in 250-ps increments for a range of 3.0 ns. The m delay shifts all outputs earlier in time, while n delay shifts all outputs later in time. Individual delays on post-scale counters (e , g , and l) provide positive delay for each output. [Table 2-21](#) shows the combined delay for each output for normal or zero delay buffer mode where Δt_e , Δt_g , or Δt_l is unique for each PLL output.

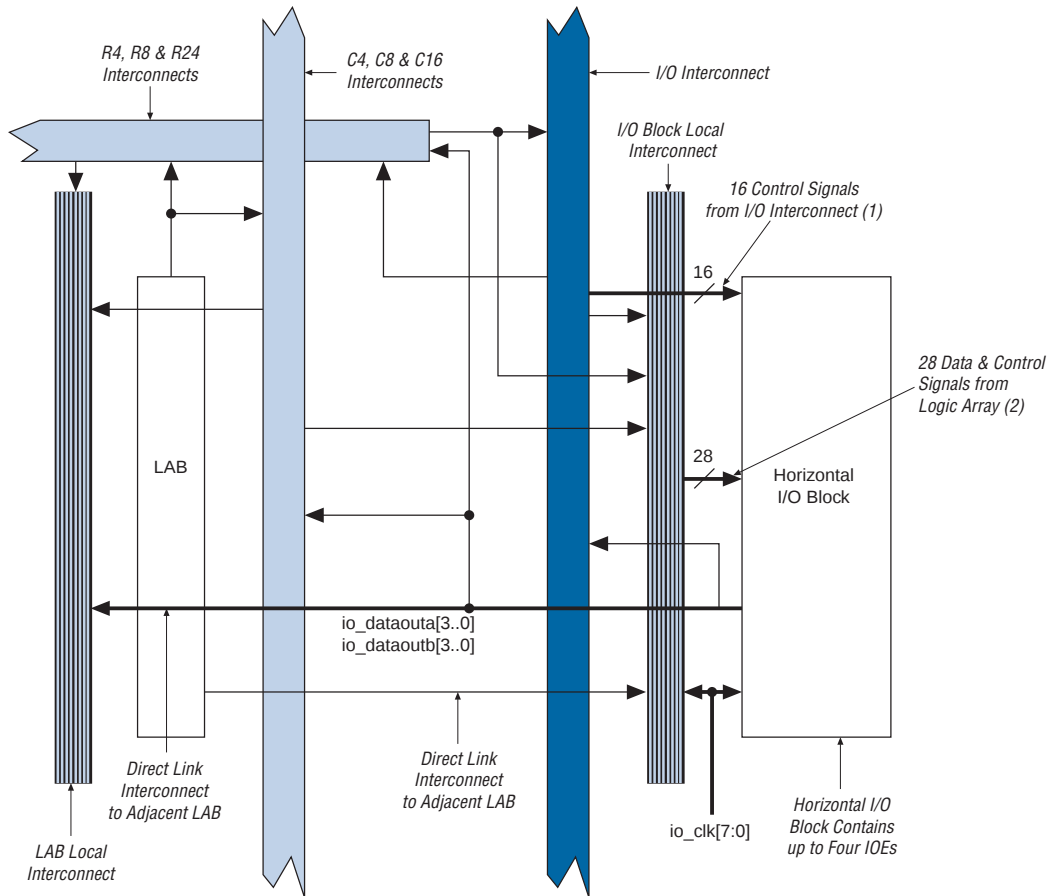
The t_{OUTPUT} for a single output can range from -3 ns to $+6$ ns. The total delay shift difference between any two PLL outputs, however, must be less than ± 3 ns. For example, shifts on two outputs of -1 and $+2$ ns is allowed, but not -1 and $+2.5$ ns because these shifts would result in a difference of 3.5 ns. If the design uses external feedback, the Δt_e delay will remove delay from outputs, represented by a negative sign (see [Table 2-21](#)). This effect occurs because the Δt_e delay is then part of the feedback loop.

Table 2-21. Output Clock Delay for Enhanced PLLs

Normal or Zero Delay Buffer Mode	External Feedback Mode
$\Delta t_{e\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_e$	$\Delta t_{e\text{OUTPUT}} = \Delta t_n - \Delta t_m - \Delta t_e$ (1)
$\Delta t_{g\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_g$	$\Delta t_{g\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_g$
$\Delta t_{l\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_l$	$\Delta t_{l\text{OUTPUT}} = \Delta t_n - \Delta t_m + \Delta t_l$

Note to [Table 2-21](#):

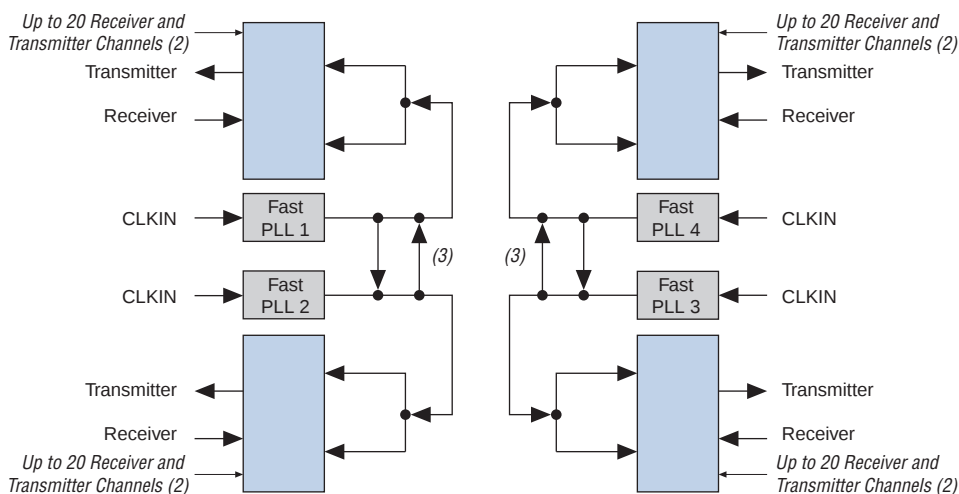
(1) Δt_e removes delay from outputs in external feedback mode.

Figure 2–60. Row I/O Block Connection to the Interconnect**Notes to Figure 2–60:**

- (1) The 16 control signals are composed of four output enables `io_boe[3..0]`, four clock enables `io_bce[3..0]`, four clocks `io_clk[3..0]`, and four clear signals `io_bclr[3..0]`.
- (2) The 28 data and control signals consist of eight data out lines: four lines each for DDR applications `io_dataouta[3..0]` and `io_dataoutb[3..0]`, four output enables `io_coe[3..0]`, four input clock enables `io_cce_in[3..0]`, four output clock enables `io_cce_out[3..0]`, four clocks `io_cclk[3..0]`, and four clear signals `io_cclr[3..0]`.

The Quartus II MegaWizard® Plug-In Manager only allows the implementation of up to 20 receiver or 20 transmitter channels for each fast PLL. These channels operate at up to 840 Mbps. The receiver and transmitter channels are interleaved such that each I/O bank on the left and right side of the device has one receiver channel and one transmitter channel per LAB row. [Figure 2-74](#) shows the fast PLL and channel layout in EP1S10, EP1S20, and EP1S25 devices. [Figure 2-75](#) shows the fast PLL and channel layout in the EP1S30 to EP1S80 devices.

Figure 2-74. Fast PLL & Channel Layout in the EP1S10, EP1S20 or EP1S25 Devices *Note (1)*



Notes to Figure 2-74:

- (1) Wire-bond packages support up to 624 Mbps.
- (2) See [Table 2-41](#) for the number of channels each device supports.
- (3) There is a multiplexer here to select the PLL clock source. If a PLL uses this multiplexer to clock channels outside of its bank quadrant, those clocked channels support up to 840 Mbps for “high” speed channels and 462 Mbps for “low” speed channels, as labeled in the device pin-outs at www.altera.com.

Operating Conditions

Stratix® devices are offered in both commercial and industrial grades. Industrial devices are offered in -6 and -7 speed grades and commercial devices are offered in -5 (fastest), -6, -7, and -8 speed grades. This section specifies the operation conditions for operating junction temperature, V_{CCINT} and V_{CCIO} voltage levels, and input voltage requirements. The voltage specifications in this section are specified at the pins of the device (and not the power supply). If the device operates outside these ranges, then all DC and AC specifications are not guaranteed. Furthermore, the reliability of the device may be affected. The timing parameters in this chapter apply to both commercial and industrial temperature ranges unless otherwise stated.

Tables 4–1 through 4–8 provide information on absolute maximum ratings.

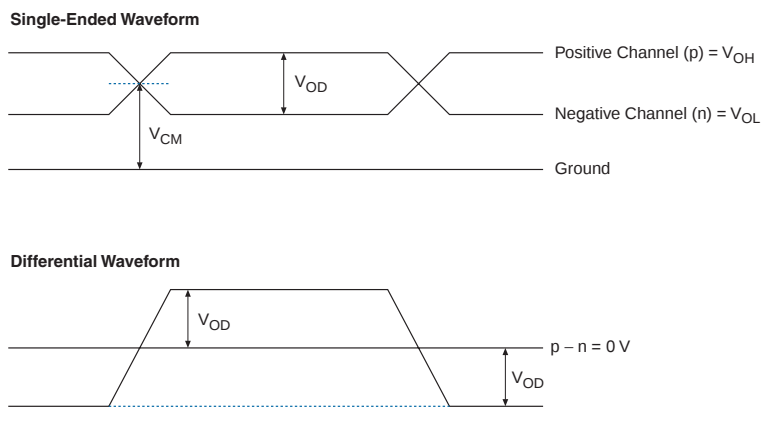
Table 4–1. Stratix Device Absolute Maximum Ratings Notes (1), (2)

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCINT}	Supply voltage	With respect to ground	–0.5	2.4	V
V_{CCIO}			–0.5	4.6	V
V_I	DC input voltage (3)		–0.5	4.6	V
I_{OUT}	DC output current, per pin		–25	40	mA
T_{STG}	Storage temperature	No bias	–65	150	°C
T_J	Junction temperature	BGA packages under bias		135	°C

Table 4–2. Stratix Device Recommended Operating Conditions (Part 1 of 2)

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	(4)	1.425	1.575	V

Figure 4–2. Transmitter Output Waveforms for Differential I/O Standards



Tables 4–10 through 4–33 recommend operating conditions, DC operating conditions, and capacitance for 1.5-V Stratix devices.

Table 4–10. 3.3-V LVDS I/O Specifications (Part 1 of 2)

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{CCIO}	I/O supply voltage		3.135	3.3	3.465	V
V_{ID} (6)	Input differential voltage swing (single-ended)	$0.1 \text{ V} \leq V_{CM} < 1.1 \text{ V}$ $W = 1$ through 10	300		1,000	mV
		$1.1 \text{ V} \leq V_{CM} \leq 1.6 \text{ V}$ $W = 1$	200		1,000	mV
		$1.1 \text{ V} \leq V_{CM} \leq 1.6 \text{ V}$ $W = 2$ through 10	100		1,000	mV
		$1.6 \text{ V} < V_{CM} \leq 1.8 \text{ V}$ $W = 1$ through 10	300		1,000	mV

Table 4–40. M512 Block Internal Timing Microparameter Descriptions

Symbol	Parameter
t_{M512RC}	Synchronous read cycle time
t_{M512WC}	Synchronous write cycle time
$t_{M512WERESU}$	Write or read enable setup time before clock
$t_{M512WEREH}$	Write or read enable hold time after clock
$t_{M512CLKENSU}$	Clock enable setup time before clock
$t_{M512CLKENH}$	Clock enable hold time after clock
$t_{M512DATASU}$	Data setup time before clock
$t_{M512DATAH}$	Data hold time after clock
$t_{M512WADDRSU}$	Write address setup time before clock
$t_{M512WADDRH}$	Write address hold time after clock
$t_{M512RADDRSU}$	Read address setup time before clock
$t_{M512RADDRH}$	Read address hold time after clock
$t_{M512DATACO1}$	Clock-to-output delay when using output registers
$t_{M512DATACO2}$	Clock-to-output delay without output registers
$t_{M512CLKHL}$	Register minimum clock high or low time. This is a limit on the min time for the clock on the registers in these blocks. The actual performance is dependent upon the internal point-to-point delays in the blocks and may give slower performance as shown in Table 4–36 on page 4–20 and as reported by the timing analyzer in the Quartus II software.
$t_{M512CLR}$	Minimum clear pulse width

Table 4–41. M4K Block Internal Timing Microparameter Descriptions (Part 1 of 2)

Symbol	Parameter
t_{M4KRC}	Synchronous read cycle time
t_{M4KWC}	Synchronous write cycle time
$t_{M4KWERESU}$	Write or read enable setup time before clock
$t_{M4KWEREH}$	Write or read enable hold time after clock
$t_{M4KCLKENSU}$	Clock enable setup time before clock
$t_{M4KCLKENH}$	Clock enable hold time after clock
$t_{M4KBESU}$	Byte enable setup time before clock
t_{M4KBEH}	Byte enable hold time after clock
$t_{M4KDATAASU}$	A port data setup time before clock

Tables 4–79 through 4–84 show the external timing parameters on column and row pins for EP1S40 devices.

Table 4–79. EP1S40 External I/O Timing on Column Pins Using Fast Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.696		2.907		3.290		2.899		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.506	5.015	2.506	5.348	2.506	5.809	2.698	7.286	ns
t_{xZ}	2.446	4.889	2.446	5.216	2.446	5.685	2.638	7.171	ns
t_{ZX}	2.446	4.889	2.446	5.216	2.446	5.685	2.638	7.171	ns

Table 4–80. EP1S40 External I/O Timing on Column Pins Using Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.413		2.581		2.914		2.938		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.668	5.254	2.668	5.628	2.668	6.132	2.869	7.307	ns
t_{xZ}	2.608	5.128	2.608	5.496	2.608	6.008	2.809	7.192	ns
t_{ZX}	2.608	5.128	2.608	5.496	2.608	6.008	2.809	7.192	ns
t_{INSUPLL}	1.385		1.376		1.609		1.837		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.117	2.382	1.117	2.552	1.117	2.504	1.117	2.542	ns
t_{xZPLL}	1.057	2.256	1,057	2.420	1.057	2.380	1.057	2.427	ns
t_{ZXPLL}	1.057	2.256	1,057	2.420	1.057	2.380	1.057	2.427	ns

Table 4–87. EP1S60 External I/O Timing on Column Pins Using Global Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.000		2.152		2.441		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	3.051	5.900	3.051	6.340	3.051	6.977	NA	NA	ns
t_{XZ}	2.991	5.774	2.991	6.208	2.991	6.853	NA	NA	ns
t_{ZX}	2.991	5.774	2.991	6.208	2.991	6.853	NA	NA	ns
t_{INSUPLL}	1.315		1.362		1.543		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.029	2.196	1.029	2.303	1.029	2.323	NA	NA	ns
t_{XZPLL}	0.969	2.070	0.969	2.171	0.969	2.199	NA	NA	ns
t_{ZXPLL}	0.969	2.070	0.969	2.171	0.969	2.199	NA	NA	ns

Table 4–88. EP1S60 External I/O Timing on Row Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	3.144		3.393		3.867		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.643	5.275	2.643	5.654	2.643	6.140	NA	NA	ns
t_{XZ}	2.670	5.329	2.670	5.710	2.670	6.208	NA	NA	ns
t_{ZX}	2.670	5.329	2.670	5.710	2.670	6.208	NA	NA	ns

Table 4–106. Stratix I/O Standard Output Delay Adders for Fast Slew Rate on Row Pins (Part 2 of 2)

Parameter		-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
1.5-V LVTTTL	2 mA		5,460		5,733		5,733		5,733	ps
	4 mA		2,690		2,824		2,824		2,824	ps
	8 mA		1,398		1,468		1,468		1,468	ps
GTL+			6		6		6		6	ps
CTT			845		887		887		887	ps
SSTL-3 Class I			638		670		670		670	ps
SSTL-3 Class II			144		151		151		151	ps
SSTL-2 Class I			604		634		634		634	ps
SSTL-2 Class II			211		221		221		221	ps
SSTL-18 Class I			955		1,002		1,002		1,002	ps
1.5-V HSTL Class I			733		769		769		769	ps
1.8-V HSTL Class I			372		390		390		390	ps
LVDS			–196		–206		–206		–206	ps
LVPECL			–148		–156		–156		–156	ps
PCML			–147		–155		–155		–155	ps
HyperTransport technology			–93		–98		–98		–98	ps

Note to Table 4–103 through 4–106:

(1) These parameters are only available on row I/O pins.

Table 4–107. Stratix I/O Standard Output Delay Adders for Slow Slew Rate on Column Pins (Part 1 of 2)

Parameter		-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
LVCMOS	2 mA		1,822		1,913		1,913		1,913	ps
	4 mA		684		718		718		718	ps
	8 mA		233		245		245		245	ps
	12 mA		1		1		1		1	ps
	24 mA		–608		–638		–638		–638	ps

Table 4–110. Stratix IOE Programmable Delays on Row Pins *Note (1)*

Parameter	Setting	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Decrease input delay to internal cells	Off		3,970		4,367		5,022		5,908	ps
	Small		3,390		3,729		4,288		5,045	ps
	Medium		2,810		3,091		3,554		4,181	ps
	Large		173		181		208		245	ps
	On		173		181		208		245	ps
Decrease input delay to input register	Off		3,900		4,290		4,933		5,804	ps
	On		0		0		0		0	ps
Decrease input delay to output register	Off		1,240		1,364		1,568		1,845	ps
	On		0		0		0		0	ps
Increase delay to output pin	Off		0		0		0		0	ps
	On		397		417		417		417	ps
Increase delay to output enable pin	Off		0		0		0		0	ps
	On		348		383		441		518	ps
Increase output clock enable delay	Off		0		0		0		0	ps
	Small		180		198		227		267	ps
	Large		260		286		328		386	ps
	On		260		286		328		386	ps
Increase input clock enable delay	Off		0		0		0		0	ps
	Small		180		198		227		267	ps
	Large		260		286		328		386	ps
	On		260		286		328		386	ps
Increase output enable clock enable delay	Off		0		0		0		0	ps
	Small		540		594		683		804	ps
	Large		1,016		1,118		1,285		1,512	ps
	On		1,016		1,118		1,285		1,512	ps
Increase t_{ZX} delay to output pin	Off		0		0		0		0	ps
	On		1,993		2,092		2,092		2,092	ps

Note to Table 4–109 and Table 4–110:

- (1) The delay chain delays vary for different device densities. These timing values only apply to EP1S30 and EP1S40 devices. Reference the timing information reported by the Quartus II software for other devices.

Table 4–125. High-Speed I/O Specifications for Flip-Chip Packages (Part 4 of 4) Notes (1), (2)														
Symbol	Conditions	-5 Speed Grade			-6 Speed Grade			-7 Speed Grade			-8 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{DUTY}	LVDS ($J = 2$ through 10)	47.5	50	52.5	47.5	50	52.5	47.5	50	52.5	47.5	50	52.5	%
	LVDS ($J = 1$) and LVPECL, PCML, HyperTransport technology	45	50	55	45	50	55	45	50	55	45	50	55	%
t_{LOCK}	All			100			100			100			100	μs

Notes to Table 4–125:

- (1) When $J = 4, 7, 8$, and 10, the SERDES block is used.
 (2) When $J = 2$ or $J = 1$, the SERDES is bypassed.

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